

Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic			Symbol	Value	Unit
Drain-Source Voltage			V _{DSS}	-30	V
Gate-Source Voltage			V _{GSS}	±20	V
Drain Current (Note 5)	Steady State	T _A = +25°C T _A = +70°C	I _D	-7.1 -6.0	A
Pulsed Drain Current (Pulse Width ≤10μS, Duty Cycle ≤1%)			I _{DM}	-20	A

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Total Power Dissipation (Note 5)	P _D	2.5	W
Thermal Resistance, Junction to Ambient (Note 5)	R _{θJA}	50	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 6)						
Drain-Source Breakdown Voltage	BV _{DSS}	-30	—	—	V	V _{GS} = 0V, I _D = -250μA
Zero Gate Voltage Drain Current	I _{DSS}	—	—	-1	μA	V _{DS} = -30V, V _{GS} = 0V
Gate-Source Leakage	I _{GSS}	—	—	±100 ±800	nA	V _{GS} = ±20V, V _{DS} = 0V V _{GS} = ±25V, V _{DS} = 0V
ON CHARACTERISTICS (Note 6)						
Gate Threshold Voltage	V _{GS(TH)}	-1	-1.7	-2.1	V	V _{DS} = V _{GS} , I _D = -250μA
Static Drain-Source On-Resistance	R _{DS(ON)}	—	—	45 65	mΩ	V _{GS} = -10V, I _D = -6.0A V _{GS} = -4.5V, I _D = -5.0A
Forward Transconductance	g _{fs}	—	8	—	S	V _{DS} = -10V, I _D = -5.3A
Diode Forward Voltage (Note 6)	V _{SD}	-0.5	—	-1.2	V	V _{GS} = 0V, I _S = -1.7A
DYNAMIC CHARACTERISTICS						
Input Capacitance	C _{iss}	—	722	—	pF	V _{DS} = -25V, V _{GS} = 0V f = 1.0MHz
Output Capacitance	C _{oss}	—	114	—	pF	
Reverse Transfer Capacitance	C _{rss}	—	92	—	pF	
Gate Resistance	R _G	—	3.3	—	Ω	V _{DS} = 0V, V _{GS} = 0V f = 1.0MHz
SWITCHING CHARACTERISTICS (Note 7)						
Total Gate Charge	Q _G	—	6.8	—	nC	V _{DS} = -15V, V _{GS} = -4.5V, I _D = -6A
	Q _G	—	13.7	—	nC	
Gate-Source Charge	Q _{GS}	—	1.6	—	nC	V _{DS} = -15V, V _{GS} = -10V, I _D = -6A
Gate-Drain Charge	Q _{GD}	—	4.18	—		
Turn-On Delay Time	t _{D(ON)}	—	6.4	—	ns	V _{DS} = -15V, V _{GS} = -10V, I _D = -1A, R _G = 6.0Ω
Rise Time	t _R	—	5.3	—		
Turn-Off Delay Time	t _{D(OFF)}	—	26.5	—		
Fall Time	t _F	—	14.7	—		

Notes: 5. Device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square copper plate.
6. Short duration pulse test used to minimize self-heating effect.
7. Guaranteed by design. Not subject to product testing

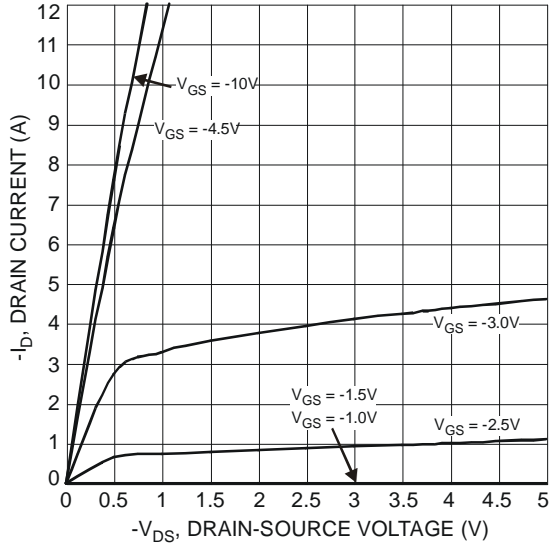


Fig. 1 Typical Output Characteristics

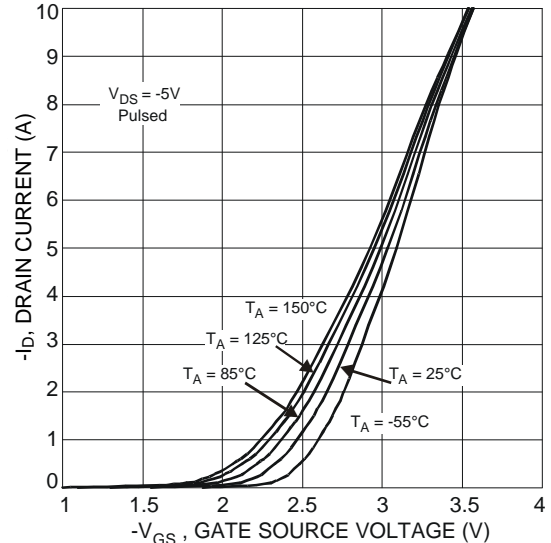


Fig. 2 Typical Transfer Characteristics

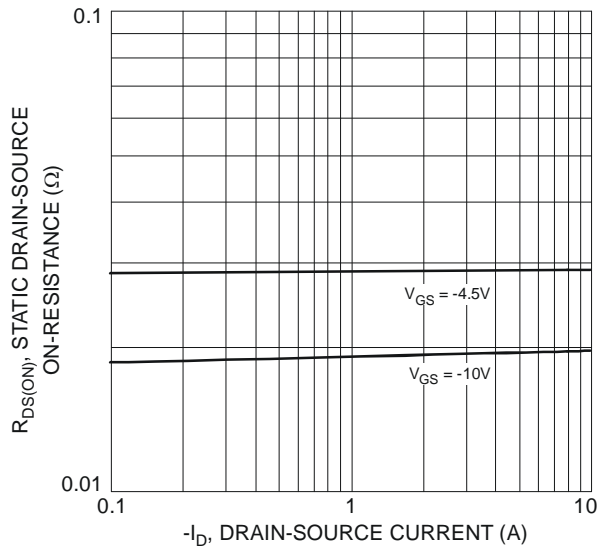


Fig. 3 On-Resistance vs. Drain Current & Gate Voltage

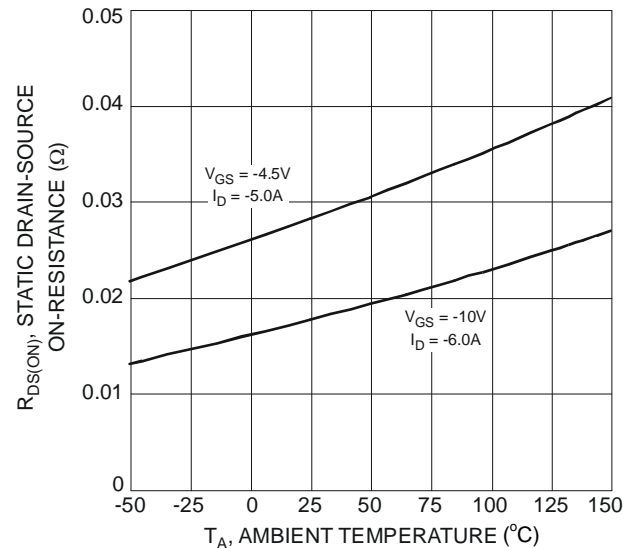


Fig. 4 Static Drain-Source On-Resistance vs. Ambient Temperature

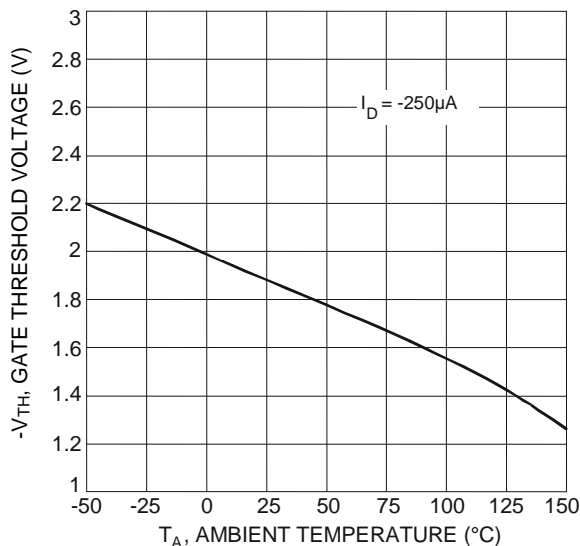


Fig. 5 Gate Threshold Variation vs. Ambient Temperature

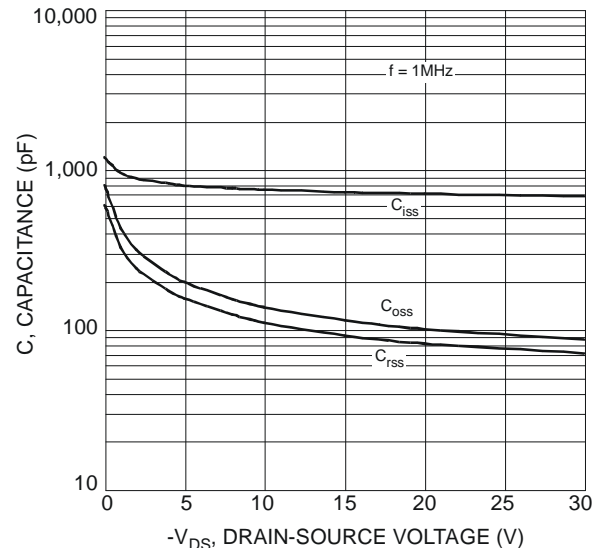


Fig. 6 Typical Total Capacitance

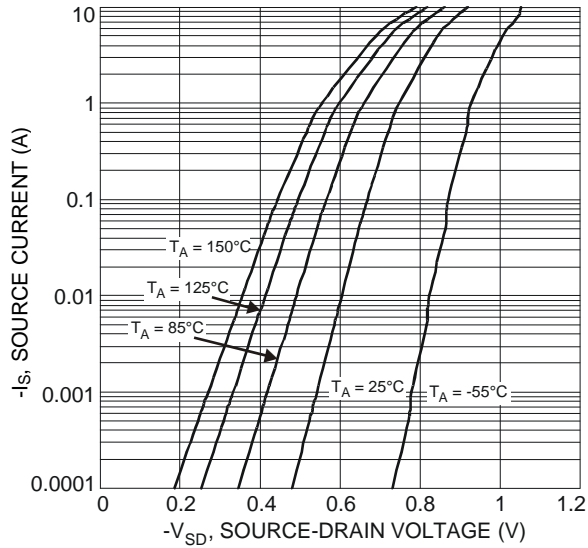


Fig. 7 Reverse Drain Current vs. Source-Drain Voltage

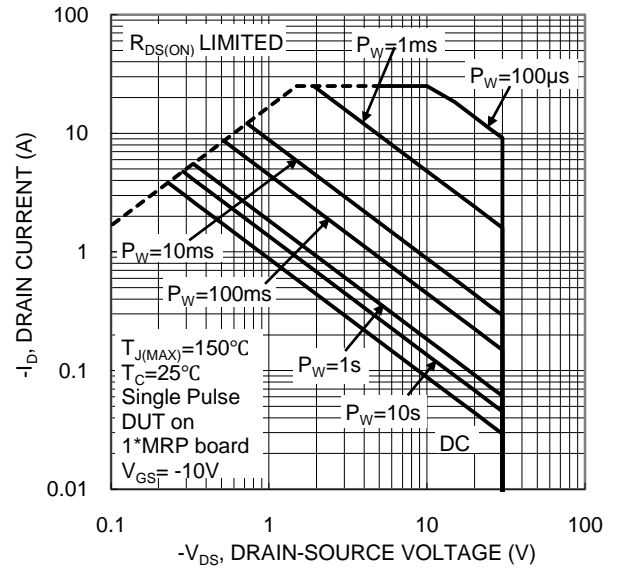


Fig. 8 SOA, Safe Operation Area

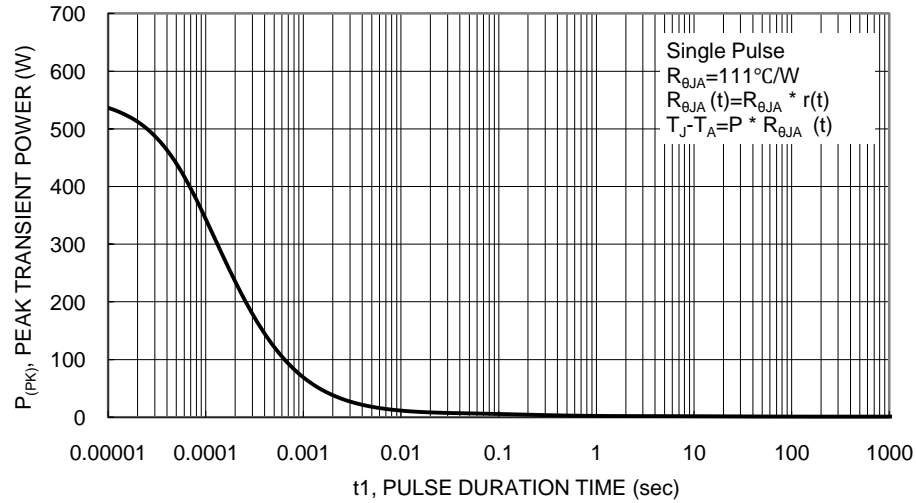


Fig. 9 Single Pulse Maximum Power Dissipation

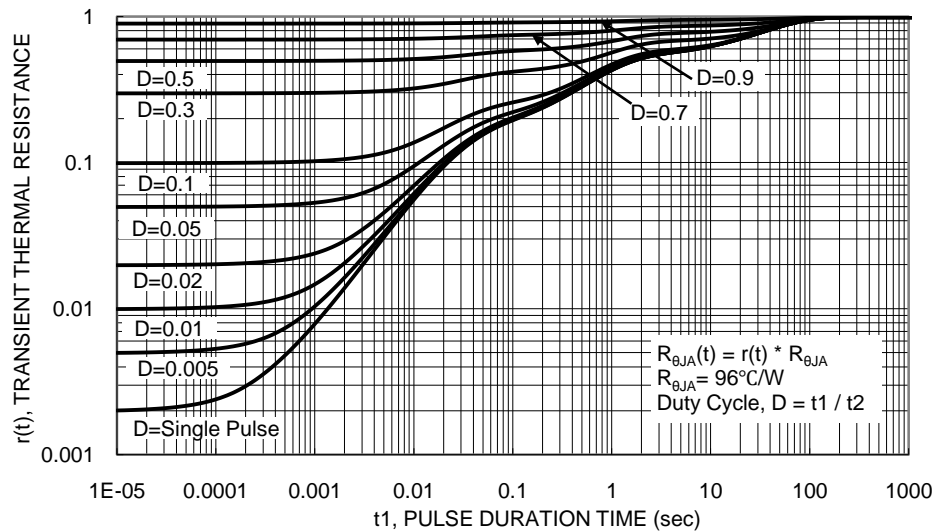
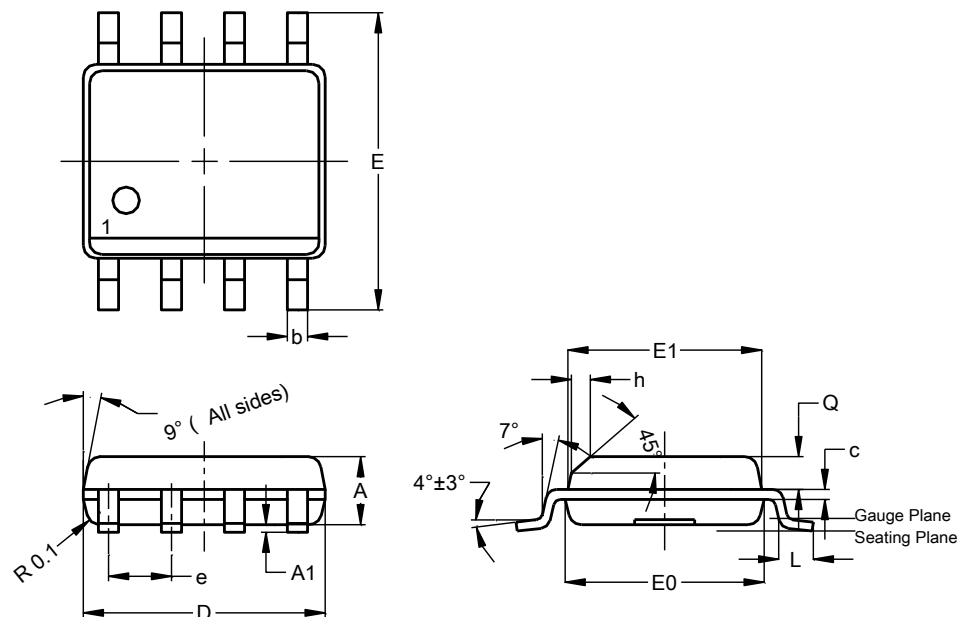


Fig. 10 Transient Thermal Resistance

Package Outline Dimensions

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

SO-8

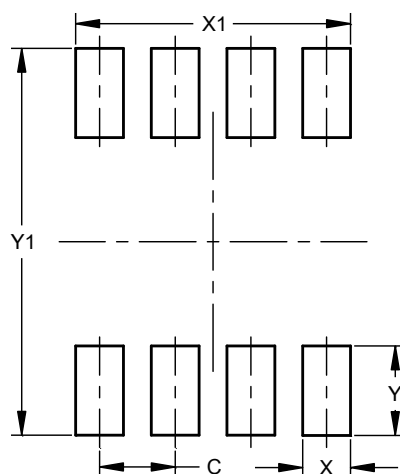


SO-8			
Dim	Min	Max	Typ
A	1.40	1.50	1.45
A1	0.10	0.20	0.15
b	0.30	0.50	0.40
c	0.15	0.25	0.20
D	4.85	4.95	4.90
E	5.90	6.10	6.00
E1	3.80	3.90	3.85
E0	3.85	3.95	3.90
e	--	--	1.27
h	-	--	0.35
L	0.62	0.82	0.72
Q	0.60	0.70	0.65
All Dimensions in mm			

Suggested Pad Layout

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

SO-8



Dimensions	Value (in mm)
C	1.27
X	0.802
X1	4.612
Y	1.505
Y1	6.50

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